Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

Claims 1-17 (Canceled).

- 18. (Original) A fabrication method, comprising the steps of: varying the history of wafers within a lot by transporting individual ones thereof within a processing tool with multiple processing chambers, among said chambers and wafer cassette and/or staging locations in various different sequences.
- 19. (Original) The method of Claim 18, further comprising the contemporaneous step of recording process sequence data for said wafers.
- 20. (Original) The method of Claim 18, further comprising the subsequent step of correlating fault and/or parametric data with process sequence data resulting from said varying step.
- 21. (Original) The method of Claim 18, further comprising the subsequent step of correlating fault and/or parametric data with process sequence data resulting from said varying step, and controlling process parameters accordingly.
- 22. (Original) A processing tool which is programmed to perform the method of Claim 1.
- 23. (Original) A processing tool which is programmed to perform the method of Claim 6.
- 24. (Original) A processing tool which is programmed to perform the method of Claim 10.

Claims 25 and 26 (Canceled).

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